

# Metal Strip Current Sensing Resistor MCS/MCSE/MCSL Series

#### **Features**

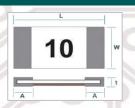
- ◆Able to withstand higher temperature and higher current
- **◆**Ultra Low sensing resistance
- **◆**Excellent frequency response
- ◆Chip size: 0402 to 2512
- **♦**Lead free, RoHS compliant for global applications and halogen free

#### **Application**

- ♦NB, Tablet Pad, PC, Smart Phone
- **♦**Battery Packs (N/B, Mobile Phone and Automobile)
- **♦**Switching power supply, Converter, Inverter
- **◆**Adapter and Chargers
- **◆**Power Module for LED Lighting and Backlights

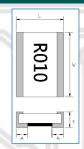
### **Electrical Specification**

1	Size	Power Rating	Resistance Range(mΩ)	Operation Temp. Range	TCR (PPM/°C)	Tolerance
	MCS0402	1/8w	M2.5~50 mΩ	-55~+17 <b>0</b> °C	±50	
	MCS0603	1/4W	M2.5~30 mΩ	<b>-55~+170</b> ℃	±50	
9	MCSE0805	1/2W	1.0~100 mΩ	-55~+170℃	±50~±75	
	MCSE1206	1W	1.0~200 mΩ	<b>-55~+170</b> ℃	±50~±100	
À			10-300 mΩ	-55~+170℃	±100	F=+/-1%
Ì	MCS2512	1W,2W	1-9 mΩ	<b>-55~+170</b> ℃	±100	G=+/-2% J=+/-5%
	MCSE4320	5W	5.0~50 mΩ	<b>-55~+170</b> ℃	±50	3-47-370
d	MCSL0508	1/2W	5~30 mΩ	-55~+170℃	±75	
	MCSL0612	1W	5~30 mΩ	<b>-55~+170</b> ℃	±100	
	MCSL1225	3W	5~10 mΩ	-55~+170℃	±50	
	MCSL2043	6W	10~20 mΩ	-55~+170℃	±50	









### Din ension

Size	Dimensions(mm)						
Size	L	W	Т	Α	В		
MCS0402	1.0±0.10	0.55±0.10	0.45±0.10	0.15±0.10	0.25±0.10		
MCS0603	1.60±0.10	0.80±0.10	0.60±0.15	0.15±0.10	0.55±0.15		
MCSE0805	2.10±0.20	1.30±0.15	0.70±0.15	0.40±0.20	0.40±0.20		
MCSE1206(S)	3.10±0.20	±0.20 1.55±0.20 0.70±0.15	0.70+0.15	0.50±0.20	0.55±0.20		
MCSE1206(L)	0.1020.20		0.7 0.20.10	0.00_00	1.10±0.20		
MCS2512(S)	2 /5 2 22	3.25±0.20	0.80±0.15	0.90±0.20	01.10±0.25		
MCS2512(L)	6.45±0.20	3.23±0.20	1.00±0.20	0.90±0.20	2.20±0.25		
MCSE4320	11.0±0.20	5.0±0.20	0.65±0.20	-	2.26±0.30		
MCSL0508	1.30±0.20	2.0±0.20	0.60±0.20		0.30±0.20		
MCSL0612	1.60±0.20	3.2±0.20	0.60±0.20	-	0.30±0.20		
MCSL1225	3.10±0.15	6.3±0.15	0.80±0.15		0.55±0.15		
MCSL2043	5.0±0.20	11.0±0.20	0.65±0.20	-	0.95±0.20		

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No	ltem	Test Condition	Specification
1	Short Time Overload	Voltage equal to 5 time rated power for 5 sec (JIS-C5202-5.5)	ΔR: ±(1% + 0.0005Ω)
2	Temperature Coefficient or(T.C.R.)	+25°C/+125°C (JIS-C5202-5.2) $TCR(ppm/°C) = \frac{\triangle R}{R \times \triangle t} \times 10^{\circ}$	As Spec.
3	Damp Heat with Load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90-95% and a temperature of 90-95% percent and a temperature of 40° ±2°C for the period of 1000 hrs. (MIL-STD-202, Method 103)	ΔR: ±(1% + 0.0005Ω)
4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 125 $^{\circ}\!$	ΔR: ±(1% + 0.0005Ω)
5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±(1% + 0.0005Ω)
6	Bending Strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2mm(+0.2/-0mm) illustrated in the figure below and hold for 10 ± 1 sec. (JIS-C5202-6.1)	ΔR: ±(1% + 0.0005Ω)
7	Resistance to solder Heat	The specimen chip shall be immersed into the flux specified in the solder bath 260 $\pm$ 5°C for 10 $\pm$ 1 sec. (MIL-STD 202,Method 210)	Solder shall be covered 95% or more of the electrode area.
8	Solder ability	The specimen chip shall be immersed into the flux specified in the solder bath 235 ±5℃ for 2 ±0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5202-6.11)	Solder shall be covered 95% or more of the electrode area.



# Metal Strip Current Sensing Resistor MCSH Series

#### **Features**

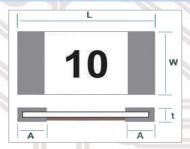
- ◆Able to withstand higher temperature and higher current
- **♦**Ultra Low sensing resistance
- **◆**Excellent frequency response
- ♦Chip size: 0603 to 2512
- **♦**Lead free, RoHS compliant for global applications and halogen free

#### **Application**

- ◆Portable Electronic Equipment-NB, Tablet PC, PC
- **♦**Battery Packs (N/B, Mobile Phone and Automobile)
- **♦**Switching power supply, Converter, Inverter
- **◆**Adapter and Chargers
- **◆PCM** for Li-on Battery pack

## **Electrical Specification**

Size	Power Rating	Resistance Range(mΩ)	Operation Temp. Range	TCR (PPM/°C)	Tolerance
0402	1/4W	2.5~30	-55~+170℃	±50	F=±1% G=±2%
0603	1/2W	2.5~50		±30	J=±5%



# Dimension

Size		Dimension	Dimensions(mm)		
Size	L	W	t	A	
0402	1.00±0.10	0.55±0.10	0.45±0.10	0.25±0.10	
0603	1.60±0.10	0.80±0.10	0.55±0.15	0.30±0.20	

No	ltem	Test Condition	Specification
1	Short Time Overload	Voltage equal to 5 time rated power for 5 sec (JIS-C5202-5.5)	ΔR: ±(1% + 0.0005Ω)
2	Temperature Coefficient or(T.C.R.)	+25°C/+125°C (JIS-C5202-5.2) $TCR(ppm/^{\circ}C) = \frac{\triangle R}{R  X  \triangle t}  x10^{\circ}$	As Spec.
3	Damp Heat with Load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90-95% and a temperature of 40±2°C for the period of 1000 hrs (MIL-STD-202, Method 103)	ΔR: ±(1% + 0.0005Ω)
4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 125±2℃ for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±(1% + 0.0005Ω)
5	Load Life	Apply rated power at 70±2°C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±(1% + 0.0005Ω)
6	Bending Strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2mm( $\pm$ 0.2/-0mm) illustrated in the figure below and hold for 10 $\pm$ 1 sec. (JIS-C5202-6.1)	ΔR: ±(1% + 0.0005Ω)
7	Resistance to solder Heat	The specimen chip shall be immersed into the flux specified in the solder bath 260±5°C for 10±1 sec. (MIL-STD-202,Method 210)	ΔR: ±(1% + 0.0005Ω)
8	Solder ability	The specimen chip shall be immersed into the flux specified in the solder bath 235 ±5°C for 2 ±0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5202-6.11)	Solder shall be covered 95% or more of the electrode area.



# **Metal Strip Current Sensing Resistor CCSH Series**

#### **Features**

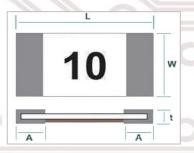
- ◆Able to withstand higher temperature and higher current
- **◆**Ultra Low sensing resistance
- **◆**Excellent frequency response
- ♦Chip size: 0603 to 2512
- **♦**Lead free, RoHS compliant for global applications and halogen free

#### **Application**

- ◆Portable Electronic Equipment-NB, Tablet PC, PC
- **♦**Battery Packs (N/B, Mobile Phone and Automobile)
- **♦**Switching power supply, Converter, Inverter
- **◆**Adapter and Chargers
- **◆PCM for Li-on Battery pack**

## **Electrical Specification**

Size	Power Rating	Resistance Range(mΩ)		Operation	TCR					
Size		1%	2%	5%	Temp. Range	(PPM/°C)				
0000	4 (0) (4)		20~99			±800				
0603	1/8W		100~499			±200				
			6~10			±800				
0805	1/4W	1/4W	1/4W	1/4W	1/4W		11~100			±400
			101~976			±200				
		6~10 -55±155°C		-55±155°C	±800					
1206	1/2W		11~100	~100		±400				
			101~976			±200				
	10~47			±300						
2512	2W		47~200			±200				
			200~910			±100				



## **Dimension**

			Dimensions(mm)		
Size	L	w	t	A	В
0603	1.55±0.10	0.85±0.10	0.45±0.10	0.30±0.20	0.35±0.20
0805	2.10±0.15	1.30±0.15	0.65±0.15	0.40±0.20	0.40±0.20
1206-S Type	3.10±0.20	1.65±0.10	0.65±0.15	0.50±0.30	0.45±0.20
1206-L Type	3.1010.20			0.80±0.30	0.4510.20
2512-S Type	6.45±0.20		0.80±0.15	0.60±0.30	0.50±0.25
2512-L Type		3.25±0.10		1.80±0.30	

No	Item	Test Condition	Specification
1	Short Time Overload	Voltage equal to 3 time rated power for 5 sec (JIS-C5202-5.5)	ΔR: ±(1% + 0.0005Ω)
2	Temperature Coefficient or(T.C.R.)	+25°C/+125°C (JIS-C5202-5.2) $TCR(ppm/^{\circ}C) = \frac{\triangle R}{R \times \triangle t} \times 10^{\circ}$	As Spec.
3	Damp Heat with Load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90-95% and a temperature of 40±2℃ for the period of 1000 hrs (MIL-STD-202, Method 103)	
4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 125±2℃ for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±(1% + 0.0005Ω)
5	Load Life	Apply rated power at 70±2℃ for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±(1% + 0.0005Ω)
6	Bending Strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2mm( $\pm$ 0.2/-0mm) illustrated in the figure below and hold for 10 $\pm$ 1 sec. (JIS-C5202-6.1)	ΔR: ±(1% + 0.0005Ω)
7	Resistance to solder Heat	The specimen chip shall be immersed into the flux specified in the solder bath 260±5°C for 10±1 sec. (MIL-STD-202,Method 210)	ΔR: ±(1% + 0.0005Ω)
8	Solder ability	The specimen chip shall be immersed into the flux specified in the solder bath 235 ±5°C for 2 ±0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5202-6.11)	Solder shall be covered 95% or more of the electrode area.



# Metal Strip Current Sensing Resistor CCS Series

#### **Features**

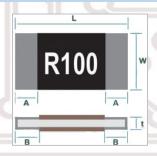
- ◆Able to withstand higher temperature and higher current
- **♦**Ultra Low sensing resistance
- **◆**Excellent frequency response
- ◆Chip size: 0603 to 2512
- **♦**Lead free, RoHS compliant for global applications and halogen free

#### **Application**

- ◆Portable Electronic Equipment-NB, Tablet PC, PC
- **♦**Battery Packs (N/B, Mobile Phone and Automobile)
- **♦**Switching power supply, Converter, Inverter
- **◆**Adapter and Chargers
- **◆**PCM for Li-on Battery pack

### **Electrical Specification**

Size	Dawer Bating	Resist	ance Rang	je(mΩ)	Operation	TCR	
Size	Power Rating	1%	2%	5%	Temp. Range	(PPM/°C)	
0402	1/16W		100~499			±500	
0402	1/1644		500~976			±200	
			100~499			±500	
0603	1/10W	1/10W		500~976			±200
		500~976		-55±155°C	±800		
		50~99			±500		
1206	1/4W		100~499		00±100 C	±200	
			500~976			±800	
			50~99			±800	
2512	1W		100~499			±500	
			500~976			±200	



# Dimension

Dimensions(mm)							
d	Size	L	w	t	A	В	
	0603	1.55±0.10	0.85±0.10	0.45±0.10	0.30±0.20	0.35±0.20	
	0805	2.10±0.15	1.30±0.15	0.65±0.15	0.40±0.20	0.40±0.20	
	1206-S Type	3.10±0.20	3.10±0.20 1.65±0.10	0.65±0.15	0.50±0.30	0.45±0.20	
à	1206-L Type	3.1010.20	1.65±0.10 0.65±0.15		0.80±0.30	0.4310.20	
	2512-S Type	0.4510.00	510.00	0.0010.45	0.60±0.30	0.5010.05	
	2512-L Type	6.45±0.20	3.25±0.10	0.80±0.15	1.80±0.30	0.50±0.25	

	No	ltem	Test Condition	Specification
I	1	Short Time Overload	Voltage equal to 3 time rated power for 5 sec (JIS-C5202-5.5)	ΔR: ±(1% + 0.0005Ω)
1	2	Temperature Coefficient or(T.C.R.)	+25°C/+125°C (JIS-C5202-5.2) $TCR(ppm/^{\circ}C) = \frac{\triangle R}{R \times \triangle t} \times 10^{\circ}$	As Spec.
	3	Damp Heat with Load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90-95% and a temperature of 40±2℃ for the period of 1000 hrs (MIL-STD-202, Method 103)	ΔR: ±(1% + 0.0005Ω)
	4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 125±2℃ for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±(1% + 0.0005Ω)
	5	Load Life	Apply rated power at 70±2°C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±(1% + 0.0005Ω)
	6	Bending Strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2mm( $\pm$ 0.2/-0mm) illustrated in the figure below and hold for 10 $\pm$ 1 sec. (JIS-C5202-6.1)	ΔR: ±(1% + 0.0005Ω)
	7	Resistance to solder Heat	The specimen chip shall be immersed into the flux specified in the solder bath 260±5°C for 10±1 sec. (MIL-STD-202,Method 210)	ΔR: ±(1% + 0.0005Ω)
	8	Solder ability	The specimen chip shall be immersed into the flux specified in the solder bath 235 ±5°C for 2 ±0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5202-6.11)	Solder shall be covered 95% or more of the electrode area.



# Metal Strip Current Sensing Resistor MCSS Series

#### **Features**

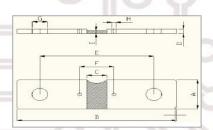
- ◆Able to withstand higher temperature and higher current
- **◆**Excellent long term stability
- •5W up to 129A at 0.3mΩ
- ♦Chip size: 2512, 3920, 59104 & 8420
- **♦**Lead free, RoHS compliant for global applications and halogen free

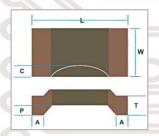
#### **Application**

- **◆**Power modules
- **♦**Frequency converters
- **♦**Current sensor for power hybrid sources
- ◆High current for automotive

### **Electrical Specification**

Size	Power Rating	Resistance Range(mΩ)	Operation Temp. Range	TCR (PPM/°C)
MCSS2512	1.5~3W	0.3~5.0	<b>-55~+170</b> ℃	±50~±150
MCSS3920	2~5W	0.2~5.0	-55~+17 <b>0</b> ℃	±50~±75
MCSS5930	6~10W	0.2~1.0	-55~+170°C	±50~±100
MCSS59104	10W	0.2	-55~+17 <b>0</b> ℃	±100
MCSS8420	15W	0.1	-55~+170°C	±100





# Dimension

Size	Dimensions(mm)					
	L	W	Т	Α	C (Max.)	P
MCSS2512	6.50±0.2	3.25±0.2	0.72±0.15	0.90±0.2	0.4	0.35±0.2
MCSS3920	10.2±0.2	5.20±0.2	0.80±0.15	1.8±0.3	0.6	0.50±0.2
MCSS5930	15.0±0.2	7.75±0.2	0.58±0.15	4.20±0.2	1.0	0.50±0.2
MCSS59104	15.0±0.2	26.5±0.2	0.58±0.2	4.5±0.2	0.9	1.0±0.2
MCSS8420	84.0±0.2	20.0±0.2	3.0±0.2	-	-	-

No	Item	Test Condition	Specification
1	Short Time Overload	Loading below condition for 5 cycles. Peak current equal 5 x rated power.	ΔR: ±(1% + 0.0005Ω)
2	Temperature Coefficient or(T.C.R.)	+25°C/+125°C (JIS-C5202-5.2) $TCR(ppm/^{\circ}C) = \frac{\triangle R}{R \times \triangle t} \times 10^{\circ}$	As Spec.
3	Moisture Resistance	The specimens shall be placed in a chamber and subjected to a relative humidity of 90-95% and a temperature of 25°C/65°C 10 cycles. (MIL-STD-202, Method 106)	ΔR: ±(1% + 0.0005Ω)
4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 125°C for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±(1% + 0.0005Ω)
5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±(1% + 0.0005Ω)
6	Bending Strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2mm( $\pm$ 0.2/-0mm) illustrated in the figure below and hold for 10 $\pm$ 1 sec. (JIS-C5202-6.1)	ΔR: ±(1% + 0.0005Ω)
7	Solder ability	The specimen chip shall be immersed into the flux specified in the solder bath 235 ±5°C for 2 ±0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5202-6.11)	Solder shall be covered 95% or more of the electrode area.